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TITLE: 1023 I/O, FC BGA, 33 X 33 PKG, 1 MM PITCH, WITH CAP ZONES			DOCUMENT NO: 98ARE10673D		REV: E	
			STANDARD: NON-JEDEC			
			SOT1618-1		05 JAN 2016	



NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. ALL DIMENSIONS ARE SYMMETRIC ACROSS THE PACKAGE CENTER LINES, UNLESS DIMENSIONED OTHERWISE.



4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARELLEL TO DATUM A.



5. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.



7. CAPACITORS MAY NOT BE PRESENT ON ALL DEVICES.



8. CAUTION MUST BE TAKEN NOT TO SHORT CAPACITORS OR EXPOSED METAL CAPACITOR PADS ON TOP OF PACKAGE.



9. PIN A1 CORNER IDENTIFICATION IS A CHAMFER FOR HICTE AND A SURFACE TRIANGLE MARK FOR PBGA..

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